

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claim 13 as follows:

**LISTING OF CLAIMS:**

Claims 1 - 11 (Canceled)

Claim 12 (Original) A method for manufacturing an electronic equipment by mounting a semiconductor device on a mounting board with projecting electrodes interposed therebetween, said semiconductor device having said projecting electrodes and a semiconductor chip both provided on a mounting side thereof, and having an electronic component provided on a side opposite to said mounting side, wherein

said semiconductor chip has a thickness smaller than a height of said projecting electrodes, said electronic component has a thickness larger than that of said semiconductor chip, and said semiconductor device is mounted on said mounting board with said projecting electrodes interposed therebetween by aligning with said mounting board said semiconductor device warped so as to be recessed on said mounting side, and pressing said semiconductor device on said mounting board with said semiconductor device being in the warped state.

Claim 13 (Currently Amended) The method for manufacturing an electronic equipment according to claim 12, wherein a linear expansion coefficient of said

electronic component is smaller than that of a wiring substrate of said semiconductor device.

Claim 14 (Original) The method for manufacturing an electronic equipment according to claim 12, wherein a value of a linear expansion coefficient of said electronic component is equal to or less than that of said semiconductor chip.

Claim 15 (Original) The method for manufacturing an electronic equipment according to claim 12, wherein said semiconductor device is manufactured by a manufacturing process including the steps of:

bonding said electronic component to a wiring substrate with heating and then cooling the resultant wiring substrate, thereby mounting said electronic component on said wiring substrate such that said wiring substrate is warped so as to be recessed on said mounting side,

mounting said semiconductor chip on said mounting side of said wiring substrate, and

forming said projecting electrodes on said mounting side of said wiring substrate.

Claims 16 - 19 (Canceled)